ACS772CB Evaluation Board User Guide

DESCRIPTION

Evaluation boards offer a method for quickly evaluating Allegro current sensors in a lab environment without needing a custom circuit board. This document describes the use of the ACS772CB Evaluation Board. This evaluation board (TED-0003440) is intended for use with the ACS772CB custom 3-pin SOIC current sensor IC.

FEATURES

• 8-layer PCB with 4 oz. copper weight on all layers

• Flexible instrument connection:

  □ Standard Keystone test points, banana jack connectors are provided

NOTE: If using the evaluation board with high currents, remove the banana jacks and use screws and lugs for connection.

EVALUATION BOARD CONTENTS

• Printed circuit board with populated components.

• Recommended bill of materials (BOM) for all compatible current sensor are listed in the "Bill of Materials" section below.

Figure 1: ASC772CB Evaluation Board

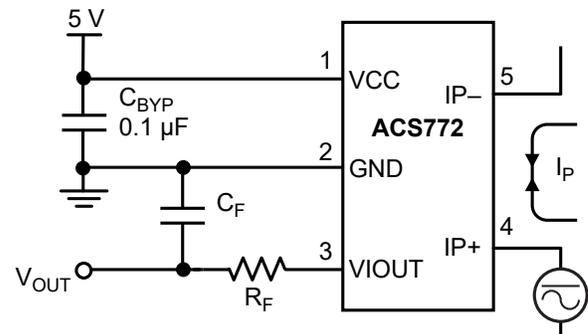**Figure 2: CB Package**

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Figure 3: ACS772 Typical Application and Pinout

USING THE EVALUATION BOARD

Evaluation Board Components

1. U1 is an CB package footprint. The ACS772 should be populated here. See yellow highlight on Figure 4.

2. U1 pins (3 to 5; see top view of EVB) allow the option to connect:

   □ C4: Load capacitor on VIOUT, can be used to decrease the bandwidth of the sensor in order to optimize noise performance.

   □ C1/C2/C3: Bypass capacitor from VCC or VIN to GND.

   □ JP1: Connects the output of U2 to VCC.

   □ See blue highlight on Figure 4 for above connection locations.

3. Test points allowing easy access to sensor pins.

   □ See Test Point locations (VOUT, GND, and VCC) highlighted in orange.

   □ See TPGND allowing easy connection to GND highlighted in orange.

4. Standard banana jack connectors IP+ and IP- (primary current mounting position) highlighted in gray. Positive current flow direction is left to right.

5. RB1, RB2, RB3, and RB4: Rubber bumper mounting positions located in top and bottom left and right hand corners. Highlighted in gray.

Evaluation Board Procedure

CONNECTING TO THE EVALUATION BOARD

The best way to connect measurement instruments to the evaluation board is to use the provided Keystone test points and banana jack connectors for the applied current.
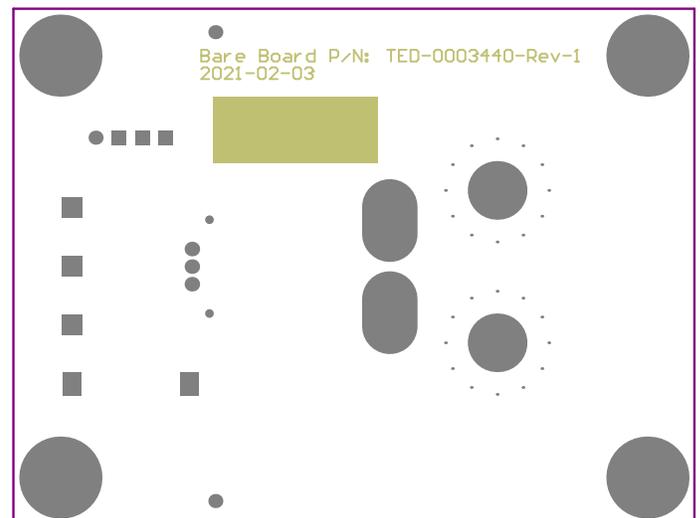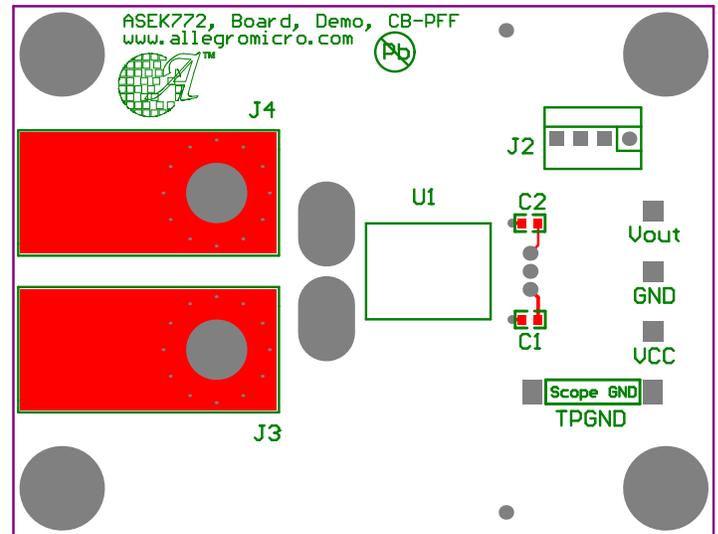

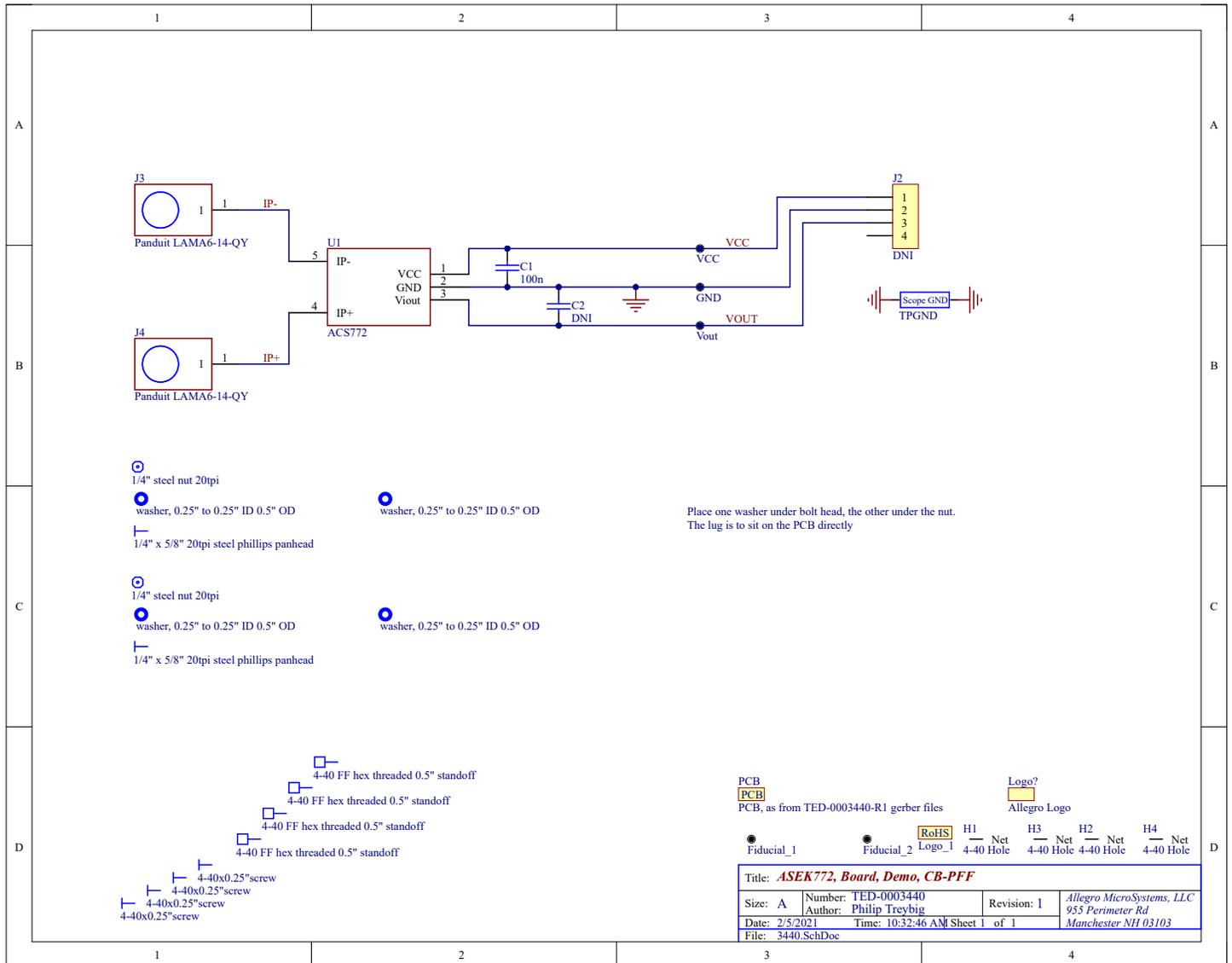**Figure 4: ASEK772 Evaluation Board Reference Images**

SCHEMATIC

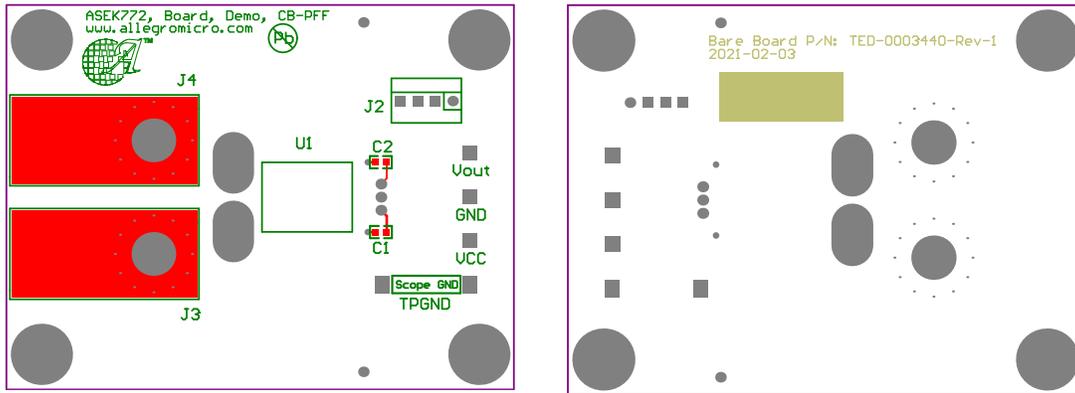**Figure 5: ASEK772 Evaluation Board Schematic**

LAYOUT

Figure 6: ASEK772 Evaluation Board Top Layer (left) and Bottom Layer (right)

Gerber files for the ASEK772 evaluation board are available for download from the Allegro website. See the technical documents section of the ACS772 device webpage.

Thermal Rise vs. Primary Current

Self-heating due to the flow of current should be considered during the design of any current sensing system. The sensor, printed circuit board (PCB), and contacts to the PCB will generate heat as current moves through the system.

The thermal response is highly dependent on PCB layout, copper thickness, cooling techniques, and the profile of the injected current. The current profile includes peak current, current on-time, and duty cycle. While the data presented in this section was collected with direct current (DC), these numbers may be used to approximate thermal response for both AC signals and current pulses.

The plot in Figure 7 shows the measured rise in steady-state die temperature of the ACS772 versus continuous current at an ambient temperature, T_A, of 25°C. The thermal offset curves may be directly applied to other values of T_A. Conversely, Figure 8 shows the maximum continuous current at a given T_A. Surges beyond the maximum current listed in Figure 8 are allowed given the maximum junction temperature, $T_{J(MAX)}$ (165°C), is not exceeded.
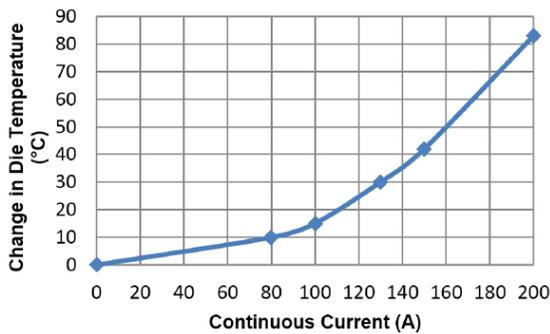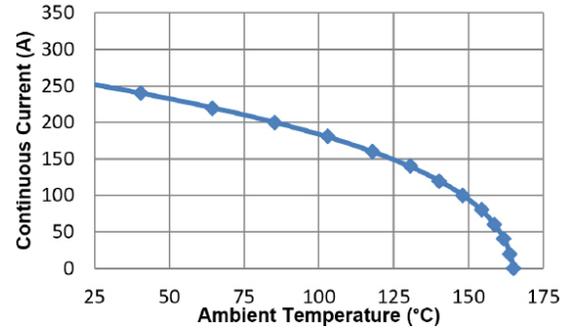

Figure 8: Maximum Continuous Current at a Given T_A

The thermal capacity of the ACS772 should be verified by the end user in the application's specific conditions. The maximum junction temperature, $T_{J(MAX)}$ (165°C), should not be exceeded. Further information on this application testing is available in the DC and Transient Current Capability application note on the Allegro website.

**Figure 7: Self-Heating in the CB Package
Due to Current Flow**

BILL OF MATERIALS

Table 1: Evaluation Board Bill of Materials

Item	Qty	S	Manufacturer	P/N	Description	Designator
1	1	9	Allegro	ACS772	IC, through-hole, current sensor	U1
2	1	6	AVX	06035C104K4T2A	Capacitor, 0603, mono, X7R, 50 V, 100 nF	C1
3	2				Do not install	C2, J2
4	2	6	Panduit	LAMA6-14-QY	Connector, through-hole, mechanical lug, 14 g to 6 g, 0.25 inch stud // comes in package of 25	J3, J4
5	3	6	Keystone	5005	Test point, thro, compact, for 62 mil PCB, red	GND, VCC, VOUT
6	1	6			Jumper, through, used as scope gnd, bend from 18 g wire, install 0.25 inches above PCB	TPGND
7	2	6			Nut, metal, 1/4" 20 tpi // package of 100	nut1, nut2
8	2	6			screw, metal, zinc-plated, panhead, phillips, 1/4" × 5/8" 20 tpi // package of 50	screw1, screw2
9	4	6	Keystone	1450C	Standoff, metal, hex-threaded, female-female, 4-40 × 0.5inch	standoff1, standoff2, standoff3, standoff4
10	4	6			Screw, metal, zinc-plated, button, slotted, 4-40 × 0.25 inch	screw1, screw2, screw3, screw4
11	4	10	McMaster-Carr	98017A655	Washer, flat, 1/4 inch, stainless // sold in package of 250 // use two per lug location	w1, w2, w3, w4
12	1	10			PCB, as from TED-0003440-R1 gerber files	PCB

RELATED LINKS AND APPLICATION SUPPORT

Table 2: Related Documentation and Application Support

Documentation	Summary	Location
Allegro Current Sensors Webpage	Product datasheet defining common electrical characteristics and performance characteristics	https://www.allegromicro.com/en/products/sense/current-sensor-ics
Allegro Current Sensor Package Documentation	Schematic files, step files, package images	https://www.allegromicro.com/en/design-support/packaging
An Effective Method for Characterizing System Bandwidth in Complex Current Sensor Applications	Application note describing methods used by Allegro to measure and quantify system bandwidth	https://allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/an-effective-method-for-characterizing-system-bandwidth-an296169
DC and Transient Current Capability/Fuse Characteristics of Surface Mount Current Sensor ICs	DC and Transient Current Capability/Fuse Characteristics of Surface Mount Current Sensor ICs	https://www.allegromicro.com/en/Insights-and-Innovations/Technical-Documents/Hall-Effect-Sensor-IC-Publications/DC-and-Transient-Current-Capability-Fuse-Characteristics.aspx
High-Current Measurement with Allegro Current Sensor IC and Ferromagnetic Core: Impact of Eddy Currents	Application note focusing on the effects of alternating current on current measurement	https://allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/an296162_a1367_current-sensor-eddy-current-core
Secrets of Measuring Currents Above 50 Amps	Application note regarding current measurement greater than 50 A	https://allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/an296141-secrets-of-measuring-currents-above-50-amps
Allegro Hall-Effect Sensor ICs	Application note describing Hall-effect principles	https://allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/allegro-hall-effect-sensor-ics
Hall-Effect Current Sensing in Electric and Hybrid Vehicles	Application note providing a greater understanding of hybrid electric vehicles and the contribution of Hall-effect sensing technology	https://allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/hall-effect-current-sensing-in-electric-and-hybrid-vehicles
Hall-Effect Current Sensing in Hybrid Electric Vehicle (HEV) Applications	Application note providing a greater understanding of hybrid electric vehicles and the contribution of Hall-effect sensing technology	https://allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/hall-effect-current-sensing-in-hybrid-electric-vehicle-hev-applications
Achieving Closed-Loop Accuracy in Open-Loop Current Sensors	Application note regarding current sensor IC solutions that achieve near closed-loop accuracy using open-loop topology	https://allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/achieving-closed-loop-accuracy-in-open-loop-current-sensors
Allegro Current Sensor ICs Can Take the Heat! Unique Packaging Options for Every Thermal Budget	Application note regarding current sensors and package selection based on thermal capabilities	https://allegromicro.com/-/media/files/application-notes/an296190-current-sensor-thermals.pdf
Explanation Of Error Specifications For Allegro Linear Hall-Effect-Based Current Sensor Ics And Techniques For Calculating Total System Error	Application note describing error sources and their effect on the current sensor output	https://allegromicro.com/-/media/files/application-notes/an296181-acs72981-error-calculation.pdf

Revision History

Number	Date	Description
–	June 21, 2023	Initial release